

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0	1.22	0.03
	Doped silicon	Silicon (Si)	7440-21-3	0.12	98.78	2.37
		<b>Subtotal</b>		<b>0.12</b>	<b>100</b>	<b>2.4</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01	10.0	0.17
	Silver alloy	Silver (Ag)	7440-22-4	0	2.0	0.03
	Lead alloy	Lead (Pb)	7439-92-1	0.07	88.0	1.51
		<b>Subtotal</b>		<b>0.08</b>	<b>100</b>	<b>1.71</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.1	100.0	2
		<b>Subtotal</b>		<b>0.1</b>	<b>100</b>	<b>2</b>
Lead Frame	Iron-nickel alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.41
	Iron-nickel alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.73	1.08	14.86
	Iron-nickel alloy	Copper (Cu)	7440-50-8	67.17	98.79	1359.35
		<b>Subtotal</b>		<b>67.92</b>	<b>99.9</b>	<b>1374.62</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.02	100.0	20.68
		<b>Subtotal</b>		<b>1.02</b>	<b>100</b>	<b>20.68</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.38	4.5	27.95
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.07	10.0	62.1
	Filler	Silica fused	60676-86-0	23.01	75.0	465.75
	Metal hydroxide	Metal hydroxide		3.07	10.0	62.1
	Carbon Black	Carbon black	1333-86-4	0.15	0.5	3.1
		<b>Subtotal</b>		<b>30.68</b>	<b>100</b>	<b>621</b>
		<b>Total</b>		<b>99.92</b>	<b>100</b>	<b>2022.41</b>

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